

Manufacturer:

Epoxy Technology

Product Name:

Epo-Tek® ET353ND Heat Cure Epoxy (2.5G)

Manufacturer Part Number: ET353ND-2.5G

>> Find Out More Details on the Epo-Tek® ET353ND Heat Cure Epoxy (2.5G) <<

Date: Fe	bruary 2021		
Rev: XX	X		
No. of Components: Tv	/0		
Mix Ratio by Weight: 10	:1		
Specific Gravity: Pa	rt A: 1.20 Part B: 1.02 S		
Pot Life: ≤:	3 Hours S		
Shelf Life- Bulk: Or	One year at room temperature		
Shelf Life- Syringe: Size	k months at -40°C		

2 Syringe: 1.18 Syringe: ≤ 2 Hours re

Recommended Cure: 150°C / 1 Hour

Minimum Alternative Cure(s): May not achieve performance properties below 150°C / 1 Minute 120°C / 5 Minutes 100°C / 10 Minutes 80°C / 30 Minutes

NOTES:

• Container(s) should be kept closed when not in use.

• Filled systems should be stirred thoroughly before mixing and prior to use.

• Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

• Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.

If product crystalizes in storage, place container in warm oven until crystallization disappears. Please refer to Tech Tip #7 on website.
TOTAL MASS SHOULD NOT EXCEED 25 GRAMS

Product Description: EPO-TEK® 353ND is a two component, high temperature epoxy designed for semiconductor, hybrid, fiber optic, and medical applications. It is one of the most popular EPO-TEK® brand products, and is known throughout the world for its performance and reliability. Also available in single component frozen syringe.

<u>Typical Properties:</u> Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results. Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

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PHYSICAL PROPERTIES:							
* Color (before cure):	Part A: Clear (Gardner < 5) Part B: Amber (Gardner < 18)						
* Consistency:		Pourabl	e liquid				
* Viscosity (23°C) @ 50 rpm:		3	,000 - 5,000	cPs			
Thixotropic Index:			N/A				
* Glass Transition Temp:		≥ 90		°C (D	ynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)		
Coefficient of Thermal Expansion (CTE):							
	Below Tg:		54		^ອ in/in°C		
	Above Tg:		206	x 10-	^³ in/in°C		
Shore D Hardness:			85				
Lap Shear @ 23°C:			> 2,000	psi			
Die Shear @ 23°C:			≥ 15	Kg	5,334 psi		
Degradation Temp:			412	°C			
Weight Loss:							
	@ 200°C:		0.22	%			
	@ 250°C:		0.39	%			
	@ 300°C:		0.87	%			
	Suggested Operating Temperature: < 350		•	ntermittent)			
Storage Modulus:			508,298	psi			
Ion Content:		CI-:	329 ppm		_		
		NH4+:	409 ppm	K⁺:	5 ppm		
* Particle Size:			N/A				
ELECTRICAL AND THERMAL PROPERTIES:							
Thermal Conductivity:			N/A				
Volume Resistivity @ 23°C:			≥ 1.8 x 10 ¹³	Ohm	-cm		
Dielectric Constant (1KHz):		3.17					
Dissipation Factor (1KHz):			0.005				
OPTICAL PROPERTIES @ 23°	C:						
Spectral Transmission:		≥	50% @ 550	nm			
			21100-1600	nm			
		≥ 98% (@ 800-1000	nm			

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

Contact the professionals at Fiber Optic Center for a quote or to get more details.

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Refractive Index (uncured):

1.5694 @589 nm

EPO-TEK® 353ND Advantages & Suggested Application Notes:

- Reasonable pot-life that allows for low temperature curing to be realized. It has an amber color change upon cure.
- Passes NASA low outgassing standard ASTM E595 with proper cure <u>http://outgassing.nasa.gov/</u>
- Semiconductor suggested applications: wafer-wafer bonding of CSP; fabrication of MEMs devices; flip chip underfill.
- Hybrid suggested applications: providing near hermetic seals and UHV seals in sensor devices, resisting high temperature packaging.
 - Down-Hole petrochemical fiber optic sensors, resisting >200°C field conditions.
- Fiber optic adhesive designed to meet Telecordia 1221 suggested applications:
 - Sealing fiber into ferrules, transmitting light in the optical pathway from 800- 1550 nm range.
 - Fiber component packaging; adhesive for active alignment of optics, environmental seal of opto-package, V-groove arrays.
- Electronics Assembly suggested applications:
 - Used as dielectric layer in the fabrication of capacitors; laminating PZT ferroelectrics found in ultrasound or ink-jetting devices.
 - Impregnating and insulating copper coil windings in motors and inductor coils. Bonding ferrite cores and magnets.
 - Structural grade epoxy found in hard-disk drive devices; bonding of SST metals, kapton, and magnets.

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